

503.43552X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SHIBATA et al

Serial No.: 10/797,003

Filed: March 11, 2004

For: Mold Die And Method For Manufacturing Semiconductor  
Device Using The Same

Art Unit: 2814

Examiner: Chambliss, A.

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116**

Mail Stop: AF  
Commissioner For Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

November 7, 2006

Sir:

This is in response to the Office Action mailed August 7, 2006, in connection with the above-identified application. The amendments are listed below and set forth on the following pages.

Amendments to the Claims;

Amendments to the Drawings; and

Remarks are included following the amendments.